

### General Description

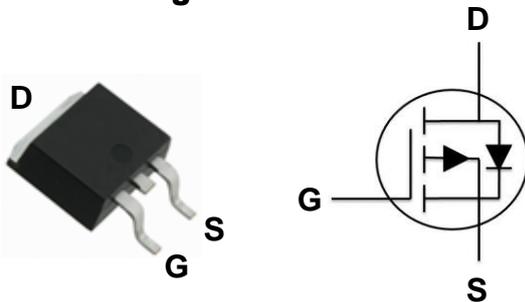
These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BVDSS	R <sub>DS(ON)</sub>	ID
-100V	95mΩ	-18A

### Features

- -100V,-18A, R<sub>DS(ON)</sub> 95mΩ@V<sub>GS</sub> = -10V
- V<sub>GS</sub> Guarantee ± 25V
- Improved dv/dt capability
- Fast switching
- Green Device Available

### TO252 Pin Configuration



### Applications

- Networking
- Load Switch
- LED applications



### Absolute Maximum Ratings (T<sub>c</sub>=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	-100	V
V <sub>GS</sub>	Gate-Source Voltage	±25	V
I <sub>D</sub>	Drain Current – Continuous (T <sub>c</sub> =25°C)	-18	A
	Drain Current – Continuous (T <sub>c</sub> =100°C)	-11.4	A
I <sub>DM</sub>	Drain Current – Pulsed <sup>1</sup>	-72	A
P <sub>D</sub>	Power Dissipation (T <sub>c</sub> =25°C)	73.5	W
	Power Dissipation – Derate above 25°C	0.59	W/°C
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJC</sub>	Thermal Resistance Junction to Case	---	1.7	°C/W
R <sub>θJA</sub>	Thermal Resistance Junction to ambient	---	62	°C/W

## Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

### Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =-250uA	-100	---	---	V
ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C, I <sub>D</sub> =-1mA	---	0.06	---	V/°C
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =-100V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	-1	uA
		V <sub>DS</sub> =-80V, V <sub>GS</sub> =0V, T <sub>J</sub> =125°C	---	---	-10	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±25V, V <sub>DS</sub> =0V	---	---	±100	nA

### On Characteristics

R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =-10V, I <sub>D</sub> =-6A	---	75	95	mΩ
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-3A	---	80	110	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250uA	-1.2	-1.6	-2.2	V
ΔV <sub>GS(th)</sub>	V <sub>GS(th)</sub> Temperature Coefficient		---	-4.46	---	mV/°C

### Dynamic and switching Characteristics

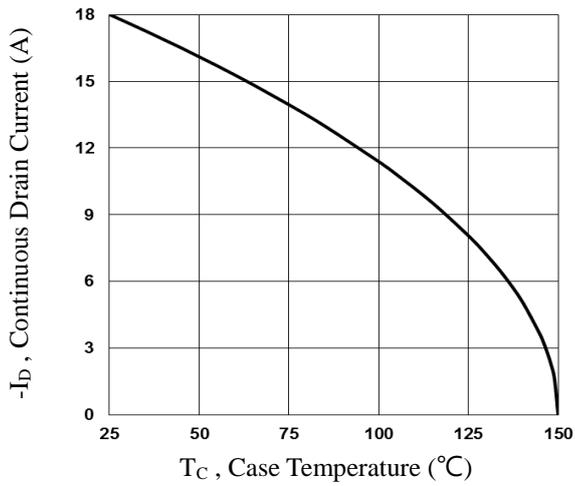
Q <sub>g</sub>	Total Gate Charge <sup>2, 3</sup>	V <sub>DS</sub> =-50V, V <sub>GS</sub> =-10V, I <sub>D</sub> =-6A	---	40.4	70	nC
Q <sub>gs</sub>	Gate-Source Charge <sup>2, 3</sup>		---	7.7	15	
Q <sub>gd</sub>	Gate-Drain Charge <sup>2, 3</sup>		---	6.6	13	
T <sub>d(on)</sub>	Turn-On Delay Time <sup>2, 3</sup>	V <sub>DD</sub> =-30V, V <sub>GS</sub> =-10V, R <sub>G</sub> =6Ω I <sub>D</sub> =-1A	---	27	54	ns
T <sub>r</sub>	Rise Time <sup>2, 3</sup>		---	12	24	
T <sub>d(off)</sub>	Turn-Off Delay Time <sup>2, 3</sup>		---	150	300	
T <sub>f</sub>	Fall Time <sup>2, 3</sup>		---	45	90	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =-30V, V <sub>GS</sub> =0V, F=1MHz	---	2250	3900	pF
C <sub>oss</sub>	Output Capacitance		---	130	250	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	90	180	
R <sub>g</sub>	Gate resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, F=1MHz	---	10	---	Ω

### Drain-Source Diode Characteristics and Maximum Ratings

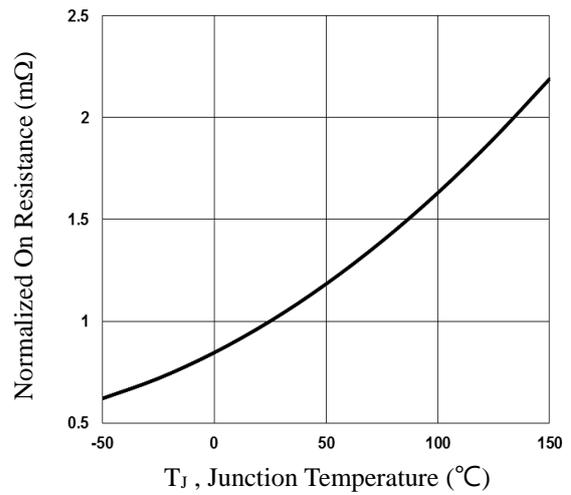
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	-18	A
I <sub>SM</sub>	Pulsed Source Current		---	---	-36	A
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =-1A, T <sub>J</sub> =25°C	---	---	-1.2	V

Note :

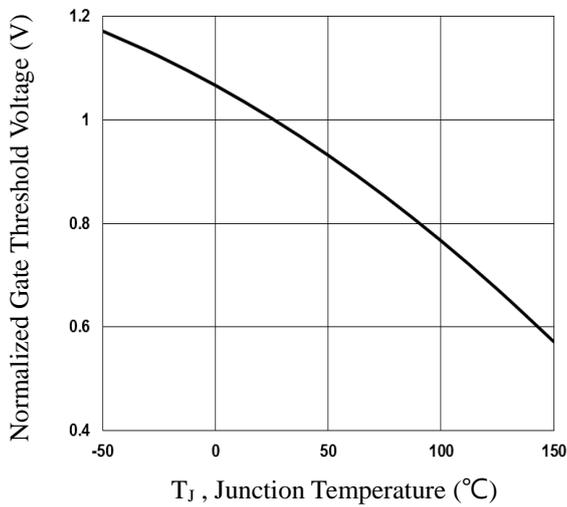
1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
3. Essentially independent of operating temperature.



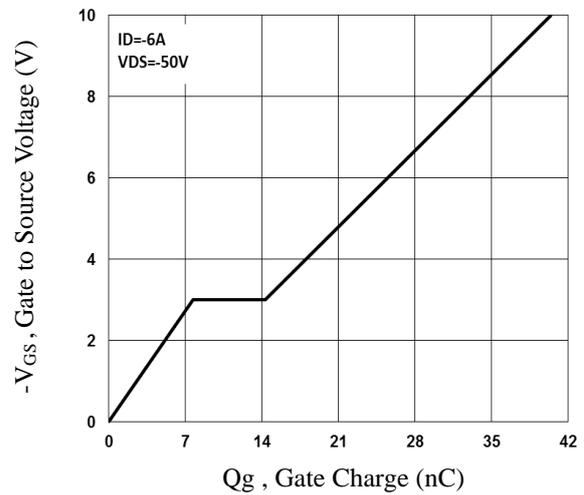
**Fig.1 Continuous Drain Current vs.  $T_c$**



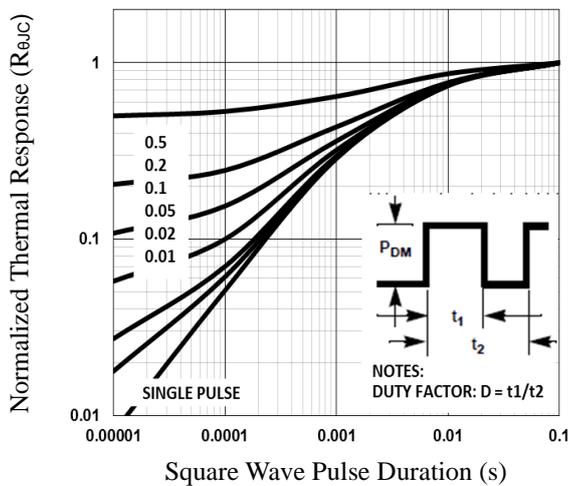
**Fig.2 Normalized  $R_{DS(on)}$  vs.  $T_j$**



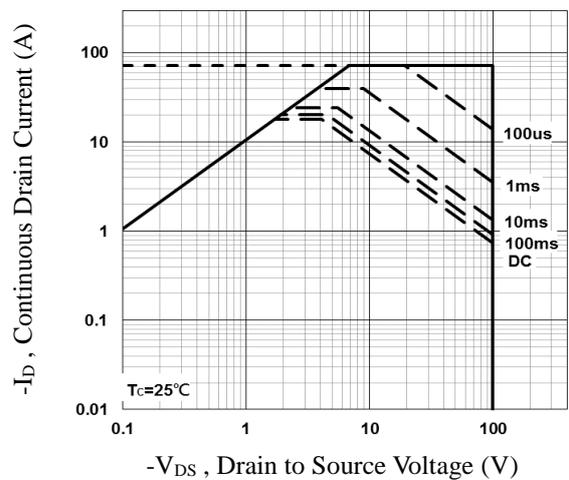
**Fig.3 Normalized  $V_{th}$  vs.  $T_j$**



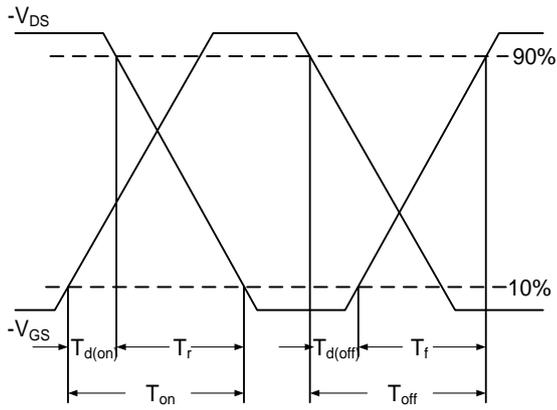
**Fig.4 Gate Charge Waveform**



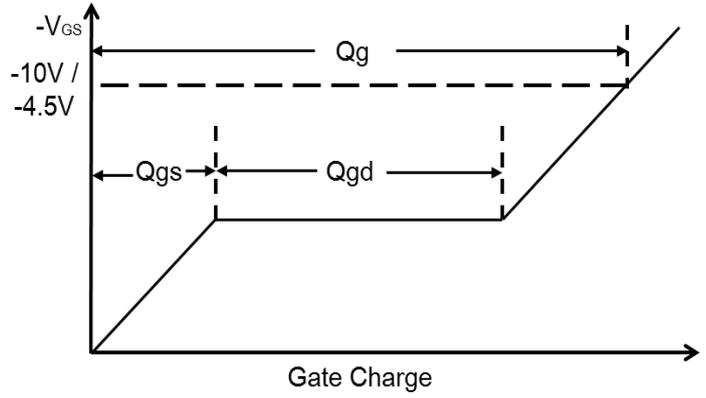
**Fig.5 Normalized Transient Impedance**



**Fig.6 Maximum Safe Operation Area**



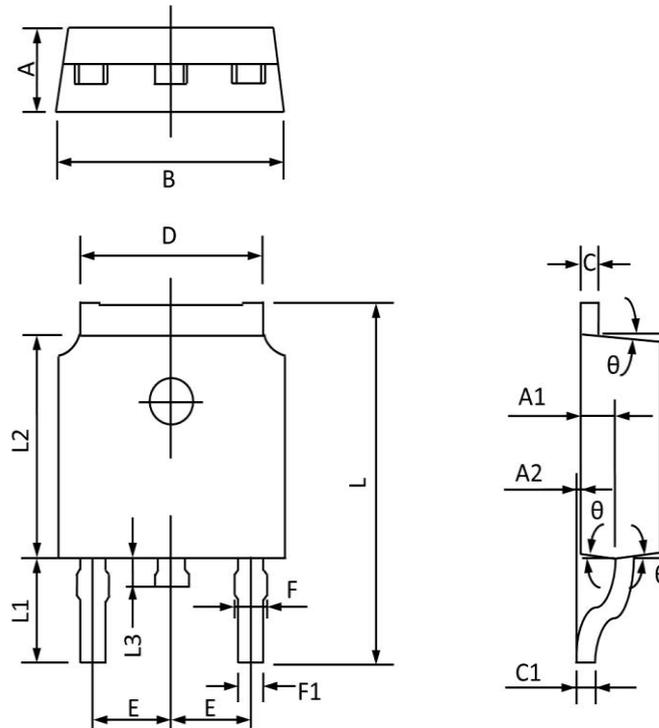
**Fig.7 Switching Time Waveform**



**Fig.8 Gate Charge Waveform**



## TO252 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	2.400	2.200	0.094	0.087
A1	1.110	0.910	0.044	0.036
A2	0.150	0.000	0.006	0.000
B	6.800	6.400	0.268	0.252
C	0.580	0.450	0.023	0.018
C1	0.580	0.460	0.023	0.018
D	5.500	5.100	0.217	0.201
E	2.386	2.186	0.094	0.086
F	1.140	0.600	0.045	0.024
F1	0.880	0.500	0.035	0.020
L	10.400	9.400	0.409	0.370
L1	3.000	2.400	0.118	0.094
L2	6.223	5.400	0.245	0.213
L3	1.200	0.600	0.047	0.024
θ	9°	3°	9°	3°